SunLED
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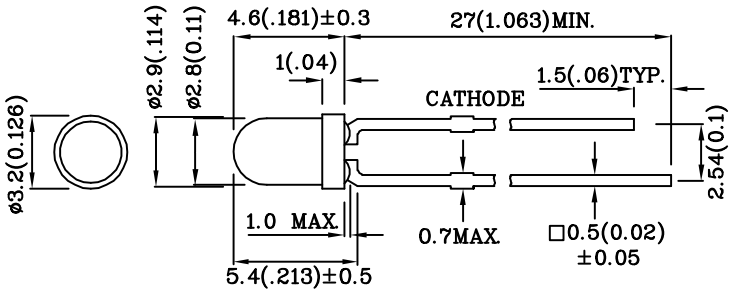
Part Number: XLUY11D14V

T-1 (3mm) SOLID STATE LAMP

Features

- LOW POWER CONSUMPTION.
- POPULAR T-1 DIAMETER PACKAGE.
- GENERAL PURPOSE LEADS.
- RELIABLE AND RUGGED.
- LONG LIFE - SOLID STATE RELIABILITY.
- AVAILABLE ON TAPE AND REEL.
- 14V INTERNAL RESISTOR.
- RoHS COMPLIANT.



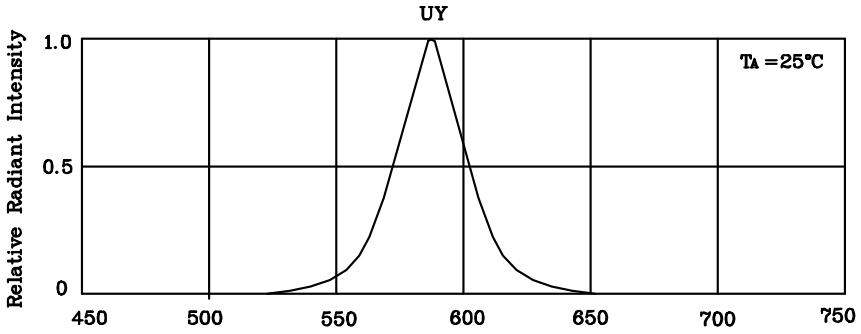
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.

Absolute maximum ratings (T_A=25°C)		**UY (GaAsP/ GaP)**	**Unit**
Reverse voltage	V_R	5	V
Forward voltage	V_F	16	V
Power dissipation	P_T	160	mW
Operating temperature	T_A	-40 ~ +70	°C
Storage temperature	Tstg	-40 ~ +85	
Lead solder temperature [2mm below package base]	260°C For 3 Seconds		
Lead solder temperature [5mm below package base]	260°C For 5 Seconds		

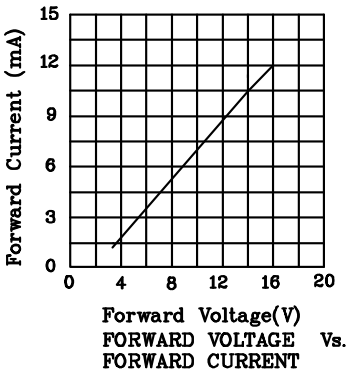
Operating Characteristics (T_A=25°C)		**UY (GaAsP/ GaP)**	**Unit**
Forward current (typ.) (VF=14V)	I_F	10.5	mA
Forward current (max.) (VF=14V)	I_F	13.5	mA
Reverse current (V_R=5V)	I_R	10	uA
Wavelength at peak emission (VF=14V)	λ peak	590	nm
Wavelength of Dominant emission (VF=14V)	λ D	588	nm
Spectral Line half-width (VF=14V)	Δλ	35	nm

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (V =14V) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XLUY11D14V	Yellow	GaAsP/GaP	Yellow Diffused	3	10	590	40°

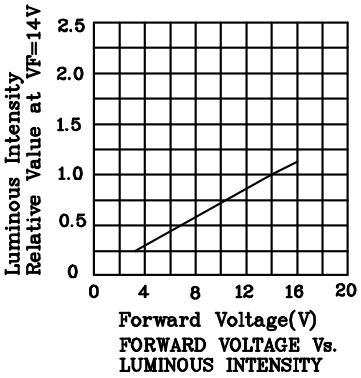


RELATIVE INTENSITY Vs. WAVELENGTH

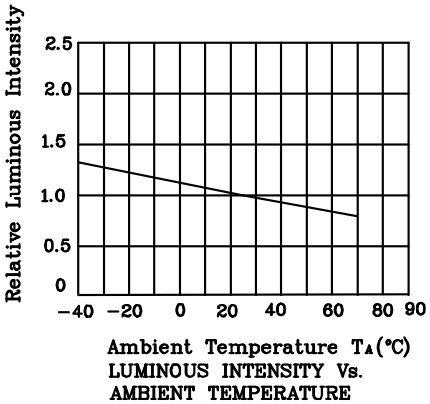
❖ **UY**



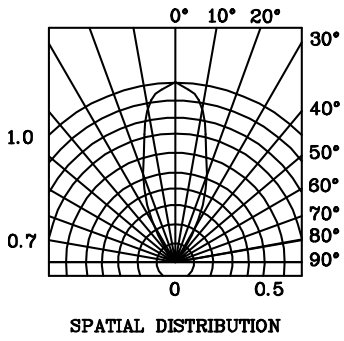
FORWARD VOLTAGE Vs. FORWARD CURRENT



FORWARD VOLTAGE Vs. LUMINOUS INTENSITY



LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

Remarks:

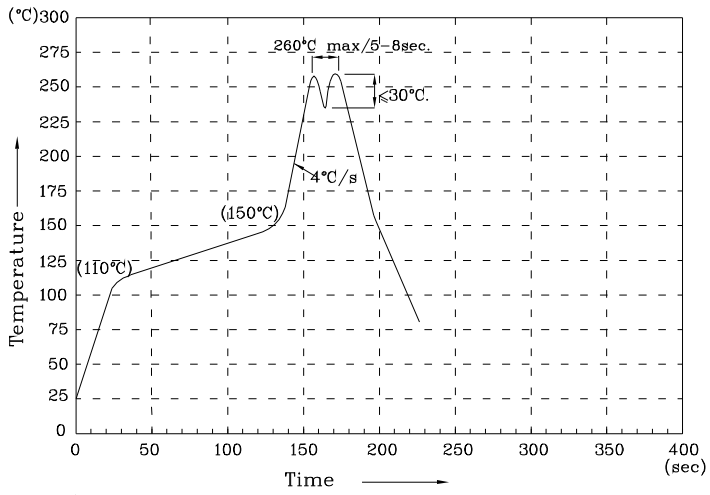
If special sorting is required (e.g. binning based on luminous intensity or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%

Note: Accuracy may depend on the sorting parameters.

XLUY11D14V

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245℃~260℃. The maximum soldering temperature should be less than 260℃.
2. Do not apply stress on epoxy resins when temperature is over 85 degree℃.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.